

## IEC QUALITY ASSESSMENT SYSTEM (IECQ) covering Electronic Components, Assemblies, Related Materials and Processes

For rules and details of the IECQ visit www.iecq.org

## Schedule of Scope to Certificate of Conformity Approved Component – Capability

IECQ Certificate No.: IECQ-C BSI 14.0050

CB Certificate No.: E086/CA

Schedule Number: IECQ-C BSI 14.0050-S Rev No.: 8 Revision Date: 2017/10/18 Page 1 of 1			
Board types: Material:	Rigid Single and double sided Rigid Double sided with plated Rigid Multilayer Epoxide Woven Glass	·	BS 123100-003 BS CECC 23100-801 BS 123200-003 BS CECC 23200-801 BS 123300-003 BS CECC 23300-801
Board Size:	584 mm x 432 mm		
No. of Layers:	24 Maximum		
Conductors:	Minimum Width Minimum Spacing	100 μm  ±50 μm 100 μm  ±50 μm	
Plated-through hole:	Minimum Diameter	0.2 mm finished he	ble
Aspect Ratio:	12.5:1 Maximum		
Finishes:	<ul> <li>Hot Air Solder Levelling</li> <li>Immersion Silver</li> <li>Electroless Nickel; Immersion Gold</li> <li>2.5 μm Gold on 5 μm Nickel Edge Contacts Liquid Photoimageable Solder Resist Legend; Photoimageable, Thermal Cured</li> </ul>		

\* These finishes meet the solderability requirements after accelerated ageing

Note: All references to ANSI/IPC A-600J assume Class 2 product, unless otherwise stated.

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